

# 曜凌光電股份有限公司

住址: 406 台中市敦化路 456 號 6F No.456-6, Dunhua RD., Beitun District, Taichung, Taiwan, R.O.C WEB: http://www.Raystar-Optronics.com E-mail: sales@raystar-optronics.com Tel:886-4-22911297 Fax: 886-4-22911296

# RC2004A-YHY-CSX

# **SPECIFICATION**

### CUSTOMER

:

(FOR CUSTOMER USE ONLY)

PCB VERSION:

**DATA:** 

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
ISSUED DATE:			

# RC2004A-YHY-CSX

# Contents

1.	Specification Revision History	Page 3
2.	General Specification	Page 4
3.	Module Classification Information	Page 5
4.	Interface Pin Function	Page 6
5.	Contour Drawing & Block Diagram	Page 7
6.	Function Description	Page 8
7.	Character Generator ROM Pattern	Page 11
8.	Instruction Table	Page 12
9.	Timing Characteristics	Page 13
10.	Initializing of LCM	Page 15
11.	Optical Characteristics	Page 17
12.	Absolute Maximum Ratings	Page 18
13.	Electrical Characteristics	Page 18
14.	Backlight Information	Page 19
15.	Reliability	Page 20
16.	Inspection specification	Page 21
17.	Precautions in use of LCD Modules	Page 25

# **1. Specification Revision History**

	<b>RECORDS OF REVISION</b>														
VERSION	DATE	REVISED PAGE NO.	Note												
1	2007.12.17		First issue												

### 2. General Specification

The Features of the Module is description as follow:

- Module dimension:  $98.0 \times 60.0 \times 13.6 \text{ (max.) mm}^3$
- View area:  $77.0 \times 25.2 \text{ mm}^2$
- Active area:  $70.4 \times 20.8 \text{ mm}^2$
- Number of Characters: 20 characters x 4 Lines
- Dot size:  $0.55 \times 0.55 \text{ mm}^2$
- Dot pitch:  $0.60 \times 0.60 \text{ mm}^2$
- Character size:  $2.95 \times 4.75 \text{ mm}^2$
- Character pitch:  $3.55 \times 5.35 \text{ mm}^2$
- LCD type: STN Positive, Yellow Green Transflective
- Duty: 1/16
- View direction: 6 o'clock
- Backlight Type: LED Yellow Green

### **3. Module Classification Information**

# 

		4 5 6 7 8	
Item		Descriptio	on
1	Brand : Rayst	ar Optronics Inc.	
2	Display Type	C: Character Type,	
2	Display Type	G: Graphic Type	
3	Display Font 3	Character 20 words, 4 Lines.	
4	Serials Code.	1	
		P: TN Positive, Gray	
		N : TN Negative,	
		G : STN Positive, Gray	
5	LCD Mode	Y : STN Positive, Yellow Gree	n
		B : STN Negative, Blue	
		F : FSTN Positive	
		T: FSTN Negative	
		A : Reflective, N.T, 6:00	K : Transflective, W.T,12:00
		D: Reflective, N.T, 12:00	1 : Transflective, U.T,6:00
	LCD	G: Reflective, W. T, 6:00	4 : Transflective, U.T.12:00
	Polarizer	J: Reflective, W. T, 12:00	C: Transmissive, N.T,6:00
6	Type/	0 : Reflective, U. T, 6:00	F : Transmissive, N.T,12:00
	Temperature range/ View	3 : Reflective, U. T, 12:00	I : Transmissive, W. T, 6:00
	direction	B: Transflective, N.T,6:00	L : Transmissive, W.T,12:00
		E: Transflective, N.T.12:00	2 : Transmissive, U. T, 6:00
		H: Transflective, W.T,6:00	5 : Transmissive, U.T,12:00
		N: Without backlight	Y: LED, Yellow Green
	5 11.1	P: EL, Blue green	A: LED, Amber
7	Backlight	T: EL, Green	R: LED, Red
	Туре	D: EL, White	O: LED, Orange
		F : CCFL, White	G: LED, Green
8	Special Code	CS : English and Cyrillic standa	
0	Special Code	X: Without Negative voltage ou	ıtput

# **4. Interface Pin Function**

Pin No.	Symbol	Level	Description
1	$V_{SS}$	0V	Ground
2	$V_{DD}$	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read(MPU $\rightarrow$ Module) L: Write(MPU $\rightarrow$ Module)
6	Е	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	А		LED +
16	K		LED -

### 5. Contour Drawing & Block Diagram



### 6. Function Description

The LCD display Module is built in a LSI controller, the controller has two 8-bit registers, an instruction register (IR) and a data register (DR).

The IR stores instruction codes, such as display clear and cursor shift, and address information for display data RAM (DDRAM) and character generator (CGRAM). The IR can only be written from the MPU. The DR temporarily stores data to be written or read from DDRAM or CGRAM. When address information is written into the IR, then data is stored into the DR from DDRAM or CGRAM. By the register selector (RS) signal, these two registers can be selected.

RS	R/W	Operation
0	0	IR write as an internal operation (display clear, etc.)
0	1	Read busy flag (DB7) and address counter (DB0 to DB7)
1	0	Write data to DDRAM or CGRAM (DR to DDRAM or CGRAM)
1	1	Read data from DDRAM or CGRAM (DDRAM or CGRAM to DR)

#### Busy Flag (BF)

When the busy flag is 1, the controller LSI is in the internal operation mode, and the next instruction will not be accepted. When RS=0 and R/W=1, the busy flag is output to DB7. The next instruction must be written after ensuring that the busy flag is 0.

#### Address Counter (AC)

The address counter (AC) assigns addresses to both DDRAM and CGRAM.

#### **Display Data RAM (DDRAM)**

This DDRAM is used to store the display data represented in 8-bit character codes. Its extended capacity is  $80 \times 8$  bits or 80 characters. Below figure is the relationships between DDRAM addresses and positions on the liquid crystal display.



#### Display position DDRAM address

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20

00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	<b>0</b> E	0F	10	11	12	13
40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53
14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27
54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67

4-Line by 20-Character Display

#### **Character Generator RAM (CGRAM)**

-

In CGRAM, the user can rewrite character by program. For  $5 \times 8$  dots, eight character patterns can be written, and for  $5 \times 10$  dots, four character patterns can be written.

-

Write into DDRAM the character code at the addresses shown as the left column of table 1. To show the character patterns stored in CGRAM.

### Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character patterns

#### Table 1.

For 5 \* 8 dot character patterns

Character Codes	CGRAM Address	Character Patterns	
(DDRAM data)		(CGRAM data)	
7 6 5 4 3 2 1 0	5 4 3 2 1 0	7 6 5 4 3 2 1 0	
High Low	High Low	High Low	
	0 0 0		1
		$\begin{array}{cccccccccccccccccccccccccccccccccccc$	
		* * * 0 0 0	Character
0 0 0 0 * 0 0 0		* * * 0 0 0	pattern(1)
0 0 0 0 0 0 0 0		* * * 0 0 0	
		* * * 0 0 0	
	1 1 1	* * * 0 0 0 0 0	Cursor patter:
	0 0 0	* * * 0 0 0	4
	0 0 1	* * * 0 0 0	
	0 1 0	* * *	
	0 1 1	* * * 0 0 0 0	C haracter
0 0 0 0 * 0 0 1	0 0 1 1 0 0	* * *	pattern(2)
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	
		$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	Cursor patteri
		* * * 0 0 0 0 0	
		l i i i i i	
0 0 0 0 * 1 1 1	1 1 1 1 0 0		
	1 0 1		
	1 1 0		
	1 1 1	* * *	
* 10 dot character patter	r n s		
Character Codes		Character Patterns	

For 5	*	10	d o	t cl	har	act	er	pat	tern	1 S																_
	1 7		ara D R							CGRAM Address								Character Patterns (CGRAM data)								
	7	6	5	4	3	2	1	0			5	4	3	2	1	0		7	6	5	4	3	2	1	0	]
		Н	igh			Lo	w			High Low							High					0 W	7			
	0	0	0	0	*	0	0	0			0	0	0 0 0 0 0 0 0 0 0 0	0 0 0 1 1 1 1 1	0 0 1 1 0 0 1 1 1	0 1 0 1 0 1 0 1		* * * * * *	* * * * * * *	* * * * * *	0 0 0	0 0 0 0 0	0 0 0 0 0	0 0 0 0 0	0 0 0 0	
													1 1 1	0 0 0	0 0 1	0 1 0		* * *	* *	* * *	0	0 0 0	0 0 0	0 0 0	0 0 0	ļ
	$\vdash$								-		_		1	1	1	1		*	*	*	*	*	*	*	*	

C haracter pattern

Cursor pattern

🔳 : " High "

# 7. Character Generator ROM Pattern

#### Table 2.

Upper																
4 bit Lower 4 bit	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LHHH	HLLL	HLLH	HLHL	HLHH	HHLL	HHLH	HHHL	нннн
LLLL	CG RAM (1)						••						•	-		
LLLH	CG RAM (2)													8		
LLHL	CG RAM (3)		::					<b></b> .								
LLHH	CG RAM (4)					= = =	:									
LHLL	CG RAM (5)												<b>.</b>			
LHLH	CG RAM (6)		···			<b>.</b>		II								•• ••
LHHL	CG RAM (7)					I.,.I		II					ŀQ			
LHHH	CG RAM (8)							II			-		•		•	
HLLL	CG RAM (1)							• • • • •				<b>.</b> ]	-::-:			
HLLH	CG RAM (2)							•					:-]:-		• • • • •	** * *** *
HLHL	CG RAM (3)			:: ::									:: ::	•••••		
HLHH	CG RAM (4)		•••								••••				:::	
HHLL	CG RAM (5)		:	•								<b>[</b> ]				
HHLH	CG RAM (6)			•••••								<b></b>	:			
HHHL	CG RAM (7)					••*••	ŀ";	•								
нннн	CG RAM (8)						::							::		

# 8. Instruction Table

Instruction		Instruction Code									Description	Execution time
mstruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	(fosc=270Khz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "00H" to DDRAM and set DDRAM address to "00H" from AC	1.53ms
Return Home	0	0	0	0	0	0	0	0	1	_	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	39µs
Display ON/OFF Control	0	0	0	0	0	0	1	D	С	В	Set display (D), cursor (C), and blinking of cursor (B) on/off control bit.	39µs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L		_	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	39µs
Function Set	0	0	0	0	1	DL	N	F	_	_	Set interface data length (DL:8-bit/4-bit), numbers of display line (N:2-line/1-line)and, display font type (F:5×11 dots/5×8 dots)	39µs
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39µs
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	39µs
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0µs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	43µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	43µs

\* "-": don't care

# 9. Timing Characteristics

### 9.1 Write Operation

### • Writing data from MPU



Ta=25℃, V	DD=5.0V
-----------	---------

Item	Symbol	Min	Тур	Max	Unit
Enable cycle time	T <sub>C</sub>	1200	_	_	ns
Enable pulse width	T <sub>PW</sub>	140	_		ns
Enable rise/fall time	$T_R, T_F$	_	_	25	ns
Address set-up time (RS, R/W to E)	t <sub>AS</sub>	0	_		ns
Address hold time	t <sub>AH</sub>	10	_		ns
Data set-up time	t <sub>DSW</sub>	40	_	_	ns
Data hold time	t <sub>H</sub>	10	_	_	ns

### 9.2 Read Operation

Reading data from ST7066U



Ta=25℃,	VDD=5V
---------	--------

Item	Symbol	Min	Тур	Max	Unit
Enable cycle time	T <sub>C</sub>	1200	_	_	ns
Enable pulse width (high level)	T <sub>PW</sub>	140			ns
Enable rise/fall time	$T_{R}, T_{F}$			25	ns
Address set-up time (RS, R/W to E)	t <sub>AS</sub>	0	_	_	ns
Address hold time	t <sub>AH</sub>	10	_	_	ns
Data delay time	t <sub>DDR</sub>			100	ns
Data hold time	t <sub>H</sub>	10	_	_	ns

### **10. Initializing of LCM**



4-Bit Ineterface



8-Bit Ineterface

### **11. Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V) θ	$CR \ge 2$	20		40	deg
view rungie	(H) φ	$CR \ge 2$	-30		30	deg
Contrast Ratio	CR	_	—	3	—	_
Response Time	T rise	_	—	150	200	ms
	T fall	—		150	200	ms

#### **Definition of Operation Voltage (Vop)**

#### Definition of Response Time (Tr, Tf)



#### **Conditions :**

Operating Voltage : Vop Frame Frequency : 64 HZ Viewing Angle( $\theta$ ,  $\phi$ ) :  $0^{\circ}$ ,  $0^{\circ}$ Driving Waveform : 1/N duty , 1/a bias

#### Definition of viewing $angle(CR \ge 2)$



Page 17, Total 27 Pages

# **12. Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T <sub>OP</sub>	-20		+70	°C
Storage Temperature	T <sub>ST</sub>	-30		+80	°C
Input Voltage	VI	V <sub>SS</sub>		V <sub>DD</sub>	V
Supply Voltage For Logic	VDD-V <sub>SS</sub>	-0.3		7	V
Supply Voltage For LCD	$V_{DD}$ - $V_0$	-0.3	_	13	V

### **13. Electrical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$		4.5	5.0	5.5	V
Supply Voltage For LCD	$V_{DD}$ - $V_0$	Ta=-20℃ Ta=25℃	_	4.5	5.3	V V
Input High Volt.	V <sub>IH</sub>	Ta=70°C ─	3.8 0.7 V <sub>DD</sub>		V <sub>DD</sub>	V V
Input Low Volt.	V <sub>IL</sub>		V <sub>SS</sub>	_	0.6	V
Output High Volt.	V <sub>OH</sub>		3.9		_	V
Output Low Volt.	V <sub>OL</sub>	_	—		0.4	V
Supply Current	I <sub>DD</sub>	V <sub>DD</sub> =5.0V	1.0	1.2	1.5	mA

### **14. Backlight Information**

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION	
Supply Current	ILED	224	280	420	mA	V=4.2V	
Supply Voltage	V	3.9	4.2	4.4	V	—	
Reverse Voltage	VR	—	—	10	V	-	
Luminous Intensity	IV	200	260	_	CD/M <sup>2</sup>	ILED=280mA	
Wave Length	λρ	560	570	580	nm	ILED=280mA	
Life Time	-		100000	_	Hr.	ILED≤280mA	
Color	Yellow Green						

### Specification

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

2.Drive from pin15,pin16



# 15. Reliability

	<b>Environmental Test</b>		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation $-20^{\circ}C$ $25^{\circ}C$ $70^{\circ}C$ 30min $5min$ $30min1 cycle$	-20°C /70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 15mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

#### Content of Reliability Test (wide temperature, -30°C~80°C)

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

# **16. Inspection specification**

NO	Item	Cri	iterion		AQL		
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol>					
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>					
03	LCD black spots, white spots, contamination (non-display)	3.2 Line type : (As following dr $ \begin{array}{c}  & & & \\ $	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$ rawing)         Width $W \le 0.02$ $2 < W \le 0.03$ $3 < W \le 0.05$ $5 < W$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Accept no dense 2 As round type	2.5		
04	Polarizer bubbles	to find, must check in specify direction. 0.50 1.00	Size $\Phi$ $\Phi \leq 0.20$ $0 < \Phi \leq 0.50$ $0 < \Phi \leq 1.00$ $0 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5		

NO	Item	Criterion	AQL
05	Scratches		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination         Symbols Define:       x: Chip length       y: Chip width       z: Chip thickness         x: Chip length       t: Glass thickness       a: LCD side length         L: Electrode pad length:       6.1 General glass chip :       6.1.1 Chip on panel surface and crack between panels:         Image: Chip thickness       y: Chip width       x: Chip length         Z: Chip thickness       y: Chip width       x: Chip length         Z ≤ 1/2t       Not over viewing       x ≤ 1/8a         It there are 2 or more chips, x is total length       x ≤ 1/8a         C: Chip thickness       y: Chip width       x: Chip length         A: Corner crack:       Image: Chip width       x: Chip length         Z ≤ 1/2t       Not over viewing       x ≤ 1/8a         Image: Chip thickness       y: Chip width       x: Chip length         Image: Chip thickness       y: Chip width       x: Chip length         Image: Chip thickness       y: Chip width       x ≤ 1/8a         Image: Chip thickness       y: Chip width       x ≤ 1/8a         Image: Chip thickness       y: Chip width       x ≤ 1/8a         Image: Chip thickness       y: Chip width       x ≤ 1/8a         Image: Chip thickness       y: Chip width <t< td=""><td>2.5</td></t<>	2.5



NO	Item	Criterion		
07	Cracked glass	The LCD with extensive crack is not acceptable.		
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>		
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>		
10	РСВ 、 СОВ	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> <li>10.9 The Scraping testing standard for Copper Coating of PCB</li> </ul>		
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65	

NO	Item	Criterion	AQL
12	General appearance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 LCD pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> <li>12.11 Product dimension and structure must conform to product specification sheet.</li> </ul>	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

### **17. Precautions in use of LCD Modules**

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.



	Sample	Estimate Eeedback Shoot	Page:			
LCM Sample Estimate Feedback Sheet Module Number :						
1 • Panel Specification :						
1. Panel Type :	Pass	□ NG ,				
2. View Direction :	Pass	□ NG ,				
3. Numbers of Dots :	Pass	□ NG ,				
4. View Area :	Pass	□ NG ,				
5. Active Area :	Pass	□ NG ,				
6.Operating Temperature :	Pass	□ NG ,				
7.Storage Temperature :	Pass	□ NG ,				
8.Others :						
2 <u>Mechanical Specification</u>	:					
1. PCB Size :	Pass	□ NG ,				
2.Frame Size :	Pass	□ NG ,				
3.Materal of Frame :	Pass	□ NG ,				
4.Connector Position :	Pass	□ NG ,				
5.Fix Hole Position :	Pass	□ NG ,				
6.Backlight Position :	Pass	□ NG ,				
7. Thickness of PCB:	Pass	□ NG ,				
8. Height of Frame to PCB:	Pass	□ NG ,				
9.Height of Module :	Pass	□ NG ,				
10.Others :	Pass	□ NG ,				
3 <u> </u>						
1.Pitch of Connector :	Pass	□ NG ,				
2.Hole size of Connector :	Pass	□ NG ,				
3.Mounting Hole size :	Pass	□ NG ,				
4.Mounting Hole Type :	Pass	□ NG ,				
5.Others :	Pass	□ NG ,				
4 • <u>Backlight Specification</u> :						
1.B/L Type :	Pass	□ NG ,				
2.B/L Color :	Pass	□ NG ,				
3.B/L Driving Voltage (Reference for LED Type) : Pass NG ,						
4.B/L Driving Current :	Pass	□ NG ,				
5.Brightness of B/L :	Pass	□ NG ,				
6.B/L Solder Method :	Deass Pass	□ NG ,				
7.Others:	Pass	□ NG ,				





Module Number :					
5 · Electronic Characteristics of Module					
1.Input Voltage :	Pass	□ NG ,			
2.Supply Current :	Pass	□ NG ,			
3.Driving Voltage for LCD :	Pass	□ NG ,			
4.Contrast for LCD :	Pass	□ NG ,			
5.B/L Driving Method :	Pass	□ NG ,			
6.Negative Voltage Output :	Pass	□ NG ,			
7.Interface Function :	Pass	□ NG ,			
8.LCD Uniformity :	Pass	□ NG ,			
9.ESD test :	Pass	□ NG ,			
10.Others :	Pass	□ NG ,			

6 • <u>Summary</u> :

Sales signature : \_\_\_\_\_ Customer Signature : \_\_\_\_\_

**Date :** / /

Page: 2